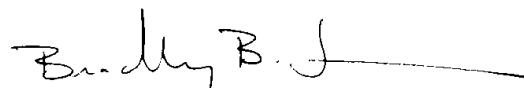


REMARKS

This amendment corrects errors in the text and drawings. Entry is respectfully solicited. This amendment is submitted prior to or concurrently with the payment of the issue fee and, therefore, no petition or fee is required. No new matter has been added.

Respectfully submitted,



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Date: March 10, 2003

BBJ/ps:djp

Enclosures: Version of Claims With Markings to Show Changes Made

Document in ProLaw

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

6. (Twice Amended) An integrated circuit package comprising:

a semiconductor die;

a lead frame including a plurality of conductors, at least some of which are coupled to the semiconductor die;

at least one alignment feature formed in the lead frame separate from the conductors and configured to facilitate positive alignment of the integrated circuit package with an external structure; and

insulating material encompassing the semiconductor die and the at least one alignment feature, the insulating material being bound by a peripheral edge, wherein the at least one alignment feature is formed and encompassed along the peripheral edge.